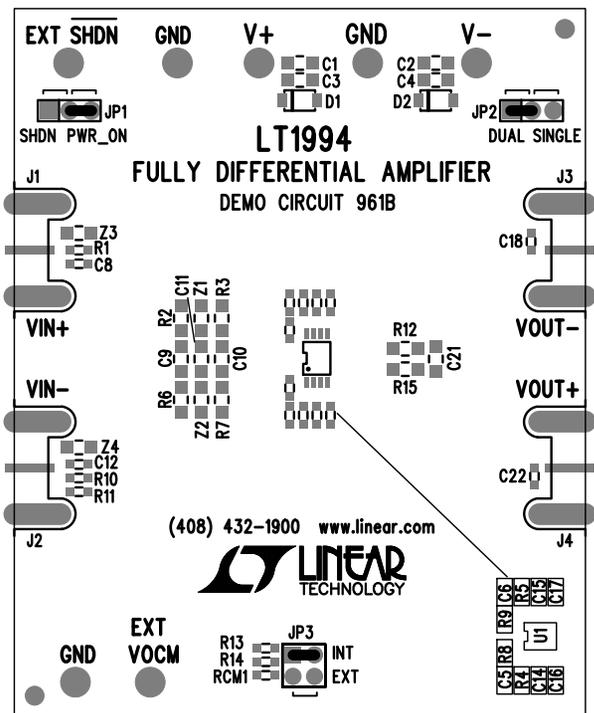


REVISION HISTORY				
ECO	REV	DESCRIPTION	APP. ENG.	DATE
-	1	PRODUCTION	PHILIP K.	08-02-16



NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
 Install Shunt on JP1 = PWR_ON
 Install Shunt on JP2 = DUAL
 Install Shunt on JP3 = INT
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.

TOP SILKSCREEN
 LINEAR TECHNOLOGY DATE: 08-02-2016
 DC961B-1 * LT1994CMS8
 FULLY DIFFERENTIAL AMPLIFIER

APPROVALS		 1630 MCCARTHY BLVD MILPITAS, CA 95035 PH: (408)432-1900 www.linear.com LTC CONFIDENTIAL- FOR CUSTOMER USE ONLY
PCB DES.	AK	
APP ENG.	PHILIP K.	TITLE: TOP ASSEMBLY DRAWING FULLY DIFFERENTIAL AMPLIFIER
		SIZE N/A IC NO. LT1994CMS8 REV. 1
SCALE = NONE	FILENAME: DC961B-1.PCB	SHT 1 OF 2